

In the Claims:

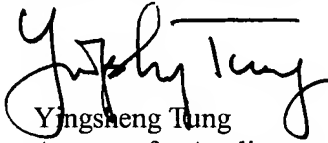
1-15. (cancelled)

16. (new) A method for forming a leadframe for use in the assembly of integrated circuit devices, comprising:
 - providing a base metal structure;
 - forming a nickel layer on the metal structure;
 - forming a solder layer on the nickel layer selectively, covering an area of said leadframe for attaching a integrated circuit chip; and
 - forming a palladium or silver layer selectively, covering an area of said leadframe suitable for attaching a bonding wire.
17. (new) The method in Claim 16 wherein the base metal structure includes copper, copper alloy, aluminum, iron-nickel alloy, or invar.
18. (new) The method in Claim 16 wherein said solder layer comprises pure tin in a matte, coarse grain, low carbon content, and annealed composition.
19. (new) The method in Claim 18 wherein said tin solder has a reflow temperature of 232 °C.
20. (new) The method in Claim 18 wherein the solder layer has a thickness in the range from about 4.0 to 6.0 μm .
21. (new) The method in Claim 16 wherein said palladium or silver layer has a thickness in the range from about 20 to 60 nm.

22. (new) A method for forming a leadframe for use with integrated circuit chips comprising:
- providing a base metal structure having a plated layer of nickel fully covering said base metal;
 - forming a layer of pure tin on said nickel layer selectively, covering an area of said leadframe suitable for attaching a circuit chip; and
 - forming a layer of palladium or silver on said nickel layer selectively, covering an area of said leadframe suitable for attaching a bonding wire.

23. (new) A method for forming a semiconductor device comprising:
- providing a leadframe including a chip-mount pad and a lead segment having a first end near said mount pad and a second end remote from said mount pad;
 - forming a nickel layer over said leadframe;
 - forming a layer of palladium on said nickel layer selectively, covering said first end of said lead segment;
 - attaching an integrated circuit chip to said mount pad; and
 - applying a layer of pure tin solder selectively, covering said second end of said lead segment.
24. (new) The method in Claim 23 further comprising bending the lead segment suitable for solder attachment.

Respectfully submitted,


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